

II. AMENDMENTS TO THE CLAIMS

This listing of the claims replaces any and all previous listings.

1-12. (Canceled)

13. (Currently amended) An integrated circuit plasma processing system comprising:

a process chamber for carrying out plasma-enhanced processing on a wafer; and

a reclamation system including:

a chemical reactive separator for non-temperature sensitive materials, receiving plasma-enhanced exhaust from the process chamber and separating chemically reactive material from the exhaust, a first separator receiving ~~plasma-enhanced~~ exhaust from the chemical reactive separator ~~process chamber~~, the first separator including a plurality of temperature zones, each temperature zone including a collection vessel for collecting material that condenses in the respective temperature zone;

a material processing unit coupled to an outlet of each collection vessel; and

a material reuse unit coupled to each material processing unit, the material reuse unit including:

a mixing chamber for receiving material from at least one

reservoir, the mixing chamber coupled to the process chamber;
an injector coupled to each reservoir for selectively
communicating material from a respective reservoir to the mixing
chamber; and
a non-reclaimed material supply coupled to the mixing
chamber.

14. (Previously presented) The apparatus of claim 13, wherein each temperature zone has a lower temperature than a preceding temperature zone.

15. (Previously presented) The apparatus of claim 13, wherein each material processing unit includes:

a disposal unit for disposing of unwanted material;
a reservoir for holding wanted material; and
a directing valve for directing material to one of the disposal unit and the reservoir.

16. (Previously presented) The apparatus of claim 15, wherein each material processing unit further includes a second separator, the second separator including at least one secondary temperature zone having a temperature different than a respective preceding temperature zone of the first separator,

wherein each secondary temperature zone includes a secondary collection vessel for collecting material that condenses in the respective secondary

temperature zone, and

wherein the directing valve directs material to one of the disposal unit, the reservoir and the second separator.

17-20. (Canceled)